

DIPLOMATE® STANDARD LOW PROFILE DIP SOCKETS ECONOMY AND STANDARD OPEN FRAME PERFORMANCE CHARACTERISTICS

Rating—250VAC; contact resistance—20 milliohms max. initial, 30 milliohms max. after test; dielectric withstanding voltage—1000VRMS min.; insulation resistance—5000 megohms min.; capacitance—0.5 picofarad max.; operating temperature—55°C to +125°C; engaging force—340 grams max.; separating force—25 grams min.; low profile—.210" above PC board; dual wiping contacts; face wipe contacts for high reliability and constant, low resistance; anti-overstress prevents contact damage; large target area, with tapered lead-in ramps, for easy DIP insertion; "True Closed Bottom" design totally prevents solder and contamination from entering contact cavity; stackable end-to-end and side-to-side ("brickwalling") for high board density; housing standoffs and slots facilitate board cleaning; visual polarization; tin or gold plated contacts; housings constructed from self-extinguishing glass-filled polyester, 940V-0 rated material. Standoffs provide board clearance for proper cleaning after soldering. Sockets are available with straight solder tails for clinching and are "true positioned" for automatic insertion into the PC board. Solder tails with retention feature, for self-retention in the PC board during handling and flow soldering, are available for hand insertion.

DUAL LEAF (DL) CONTACT SOCKETS (OPEN FRAME)

| Cat. No. | No. of Pos. | Row Pin Spacing | Net Price Per 1000 |
|----------|-------------|-----------------|--------------------|
|----------|-------------|-----------------|--------------------|

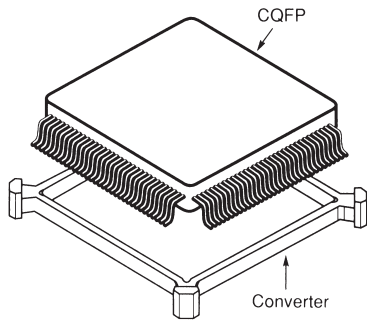
PHOSPHOR BRONZE

SOCKETS WITH STRAIGHT SOLDER TAILS

TINNED

| | | | |
|------------|----|------|----------|
| 1-390261-3 | 14 | .300 | \$116.23 |
| 1-390261-4 | 16 | .300 | 123.55 |
| 1-390261-5 | 18 | .300 | 154.94 |
| 1-390261-6 | 20 | .300 | 274.91 |
| 1-390261-7 | 22 | .300 | 244.58 |
| 1-390262-1 | 24 | .600 | 209.79 |
| 1-390262-2 | 28 | .600 | 279.84 |
| 1-390263-2 | 32 | .600 | 321.83 |
| 1-390262-5 | 40 | .600 | 446.35 |
| 1-390263-4 | 40 | .600 | 443.81 |
| 390262-7 | 48 | .600 | 523.54 |

NOTE: Tin-lead plate on solder tails.
+Over-The-Component (OTC) Style



MICRO-PITCH CONVERTER FOR CERAMIC QUAD FLAT PACKS (CQFP)

Converts ceramic package to outline configuration of a Plastic Quad Flat Pack, while firmly holding and protecting the CQFP in a MICRO-PITCH cover for ease of handling and testing. These new AMP handy converters allow Ceramic Quad Flat Packs (CQFP) to be used in 132-position Plastic Quad Flat Pack (PGFP) MICRO-PITCH sockets. The converter is molded from polyphenylene sulfide, the same high temperature composition as the mating AMP MICRO-PITCH protective cover. The low cost and simple assembly makes these units highly attractive for use with the Motorola MC68020 and similar series.

PQFP MICRO-PITCH SOCKETS

Current rating—1 amp max.; operating temperature—-55°C to +105°C; dielectric withstanding voltage—750VAC min.; capacitance (adjacent contacts)—1 picofarad max.; durability—15 insertion/withdrawal cycles; .025" centerline for high density, low cost packaging; low profile permits even higher packaging with only .375" max. height PC boards; high normal force and positive engagement increases reliability to minimize field failures; protective cover separates and safeguards IC leads during handling and insertion; closed-bottom housing aids in prevention of solder bridging between contacts; contacts absorb mating and reaction forces for board and housing protection; .020" minimum wipe contact insures reliability of tin-to-tin interface; high temperature materials; sockets can be spaced a minimum of .150" from each other. The socket's two piece design eases the problems of handling the gullwing-leaded PQFP packages. The IC is first inserted into the plastic cover and then the cover is snapped over the socket housing to insert the chip into the socket. The complete assembly presents a low profile (.375") to permit close stacking of PC boards.

PQFP SOCKETS

| Cat. No. | No. of Pos. | Net Price |
|----------|-------------|-----------|
|----------|-------------|-----------|

HOUSING SUB-ASSEMBLY

CONVENTIONAL AMP SOCKETS

| | | |
|------------|-----|---------|
| 2-821949-4 | 100 | \$22.80 |
| 2-821949-5 | 132 | 18.91 |

REPLACEMENT FOR 3M TEXT TOOL SOCKETS

| | | |
|------------|-----|-------|
| 2-822064-4 | 100 | 20.47 |
| 2-822064-5 | 132 | 32.45 |

CQFP MICRO-PITCH CONVERTER

| | | |
|----------|----------------------------|-------|
| 822054-2 | CQFP MICRO-PITCH Converter | 12.09 |
|----------|----------------------------|-------|

USE WITH MICRO-PITCH SOCKET

| | | |
|------------|----------------------|-------|
| 2-821949-5 | Housing Sub-Assembly | 18.91 |
| 821942-1 | Cover | 5.88 |

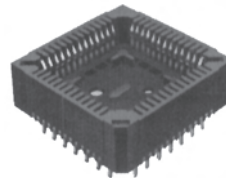
COVER

CONVENTIONAL AMP SOCKETS

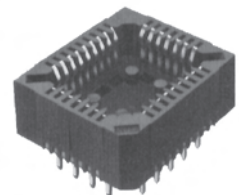
| | | |
|----------|-----|------|
| 821939-1 | 100 | 3.47 |
| 821942-1 | 132 | 5.88 |

REPLACEMENT FOR 3M TEXT TOOL SOCKETS

| | | |
|----------|-----|------|
| 821939-1 | 100 | 3.47 |
| 821942-1 | 132 | 5.88 |



SQUARE



RECTANGULAR

PLCC SOCKETS HIGH PRESSURE TIN (HPT) SOCKETS WITH SOLDER TAILS

Contact resistance—3.0 milliohms max. change after any test sequence with a 15 milliohm max. final resistance; capacitance (adjacent contact) 1.0 picofarad max.; inductance (self)—10nh max. at 500 KHz; insulation resistance—1 x 10⁴ megohms min.; dielectric withstanding voltage—600 VAC for 1.0 minute; positive locking contact design prevents package "popout"; high normal force contacts—above 200 grams to provide optimum mating and retention of PLCC's and maintain reliable interconnection; post plated contacts; staggered solder tail heights permit easy insertion into PC board; rigid solder tails protect against damage in handling and insertion, single-piece housing for easy removal; visual aids for registration; orientation holes for insertion and drainage; standoffs provide clearance for heat dissipation and cleaning and bottom loaded contacts for inspection and repair. The AMP HPT Chip Carrier Sockets are designed to make effective and economical use of available PC board area for plastic chip carriers with high pin counts.

| Cat. No. | No. of Pos. | Height Off PCB | Package Configuration | Net Price Per 1000 |
|------------|-------------|----------------|-----------------------|--------------------|
| 822473-1 | 20 | .360" | Square | \$793.77 |
| 1-822473-2 | 28 | .360" | Square | 1455.07 |
| 1-822473-3 | 32 | .360" | Rectangular | 1662.34 |
| 1-822473-4 | 44 | .360" | Square | 1056.35 |
| 822473-5 | 52 | .360" | Square | 1113.15 |
| 822473-6 | 68 | .360" | Square | 1195.60 |
| 1-822473-7 | 84 | .360" | Square | 2285.70 |



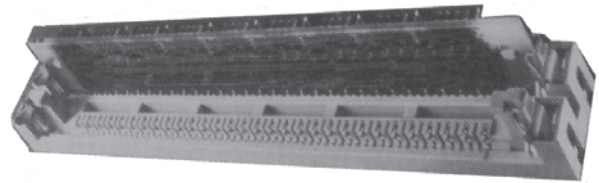
EXTRACTION TOOLS
A



B



ALL PURPOSE TOOL
PART NO. 822154-1



MICRO EDGE SIMM SOCKETS WITH METAL LATCHES FOR LEADLESS SINGLE IN-LINE MEMORY MODULES

Current rating—1 ampere max.; operating temperature— -40°C to $+150^{\circ}\text{C}$; termination resistance (dry circuit)—30 milliohms max. initial; dielectric withstanding voltage—1.5 KVAC; insulation resistance—10,000 megohms min. initial; capacitance—2.0 picofarads max.; normal force—200 grams min. tin/tin and gold/gold interface; durability 25 cycles min.; metal latches eliminate breakage; reliable contact design for durability; heat resistant housings withstand hostile environments; designed for robotic assembly to facilitate automatic manufacturing operations; positive polarization prevents mis-insertion; low insertion force for easy module insertion.

MICRO-EDGE SIMM SOCKETS

| Cat. No. | No. of Pos. | Pin Spacing | Net Price |
|----------|-------------|-------------|-----------|
|----------|-------------|-------------|-----------|

VERTICAL SINGLE ROW CONNECTORS

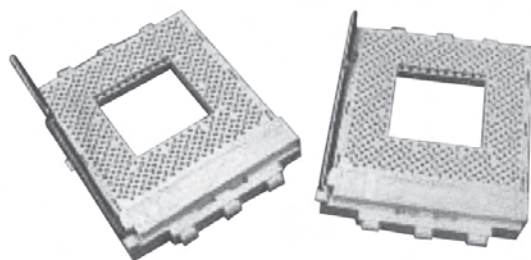
TIN PLATE, WITH CENTER POST (REVERSE POLARIZATION)

| | | | |
|-----------|----|-------|--------|
| 5822030-3 | 72 | .050" | \$5.65 |
|-----------|----|-------|--------|

TIN PLATE, WITHOUT CENTER POST

| | | | |
|-----------|----|-------|------|
| 5822019-4 | 72 | .050" | 6.29 |
|-----------|----|-------|------|

| Cat. No. | No. of Pos. | Socket Type | Tool Style | Net Price |
|--|-------------|-------------|------------|-----------|
| EXTRACTION TOOLS FOR LOW PROFILE PLCC SURFACE MOUNT | | | | |
| 822011-1 | 20 | Square | A | \$210.97 |
| 822045-1 | 28 | Square | A | 213.51 |
| 821980-1 | 32 | Rectangular | A | 89.05 |
| 821981-1 | 44 | Square | A | 89.05 |
| 822049-1 | 52 | Square | A | 215.24 |
| 822026-1 | 68 | Square | A | 89.05 |
| EXTRACTION TOOLS FOR PLCC SOCKETS WITH SOLDER TAILS | | | | |
| 821903-5 | 28 | Square | B | 124.38 |
| 821903-1 | 32 | Rectangular | B | 46.94 |
| 821981-1 | 44 | Square | B | 89.05 |
| 822049-1 | 52 | Square | B | 215.24 |
| 822026-1 | 68 | Square | B | 89.05 |
| 822268-1 | 84 | Square | B | 89.05 |
| ALL PURPOSE EXTRACTION TOOL | | | | |
| 822154-1 | — | — | C | 14.22 |



AMP SOCKET 462 (SOCKET A) ASSEMBLY LOW PROFILE

462 position. 19×19 interstitial grid. Accommodates AMD Athlon processors. Interfaces with all thermal solutions. Level actuated "zero-insertion force". Ultra low profile lever design. Accommodates approved AMD heat sinks. No actuation tooling required. Normally closed, full wipe contacts. **APPLICATIONS:** All desktop PCs and Workstations.

| Cat. No. | Solder Tail Length Inches (mm) | Net Price |
|--|--------------------------------|-----------|
| CONTACT PLATING: GOLD FLASH IN CONTACT AREA | | |
| 916788-4 | .110 (2.79) | \$3.60 |
| 916788-3 | .093 (2.36) | 4.40 |
| CONTACT PLATING: .000015 (0.00038) MIN GOLD IN CONTACT AREA | | |
| 916788-2 | .110 (2.79) | 3.71 |
| 916788-1 | .093 (2.36) | 4.66 |

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